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查询LC651104N供应商

Ordering number : EN*5221

CMOS LSI

LC65E1104

On-Chip UVEPROM



Preliminaly

Overview

The LC65E1104 is an on-chip UVEPROM version of Sanyo's LC651104N/F/L and LC651102N/F/L CMOS 4-bit single-chip microcontrollers. The LC65E1104 has the same functions and pin assignment as the LC651104N/F/L and LC651102N/F/L mask ROM products, although the A/D characteristics and certain other characteristics differ somewhat. It includes a 4-KB on-chip EPROM.

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The LC65E1104 is provided in DIC30S and MFC30S window packages and is ideal for program development and evaluation since program data can be rewritten multiple times.

Features

- EPROM data option switching
- The following four LC65E1104 functions can be specified by EPROM data:
- Port C and D output levels at reset
- Clock oscillator option
- Clock predivider option
- Watchdog reset option

However, note that the port output circuit type cannot be changed. These circuits are always open-drain outputs.

- Internal UVEPROM capacity: 4096 bytes
- The LC65E1104 on-chip UVEPROM can be programmed and verified using a general-purpose EPROM programmer.

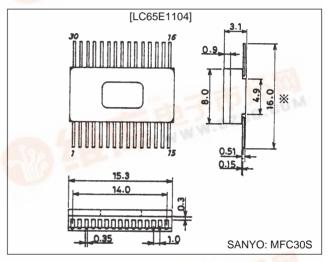
Sanyo provides special-purpose 30-to-28-pin adapters (the W65EP1104D for the DIC package and the W65EP1104M for the MFC package) to allow commercial EPROM programmers to be used with the LC65E1104.

- · Data security function
- Pin compatible with the LC651104/1102 mask ROM devices
- Instruction cycle time: 0.92 µs to 20 µs (A/D converter cycle time: 0.98 µs to 12 µs)
- Factory shipment: DIC-30S (with window), MFC-30S (with window)

Package Dimensions

unit: mm

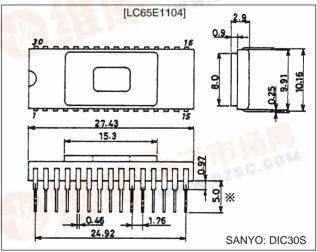
3212-MFC30S



4-Bit Single-Chip Microcontroller

unit: mm

3215-DIC30S



These figures are provided for reference purposes and do not include Note: tolerance specifications. Official drawings are available on request from your Sanvo representative.

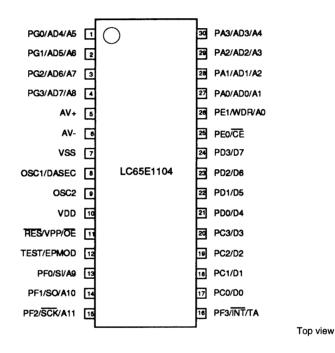
SANYO Electric Co., Ltd. Semiconductor Bussiness Headquarters TOKYO OFFICE Tokyo Bldg., 1-10, 1 Chome, Ueno, Taito-ku, TOKYO, 110 JAPAN

LC651104/1102 series organization

Model name	Pins	ROM capacity	RAM capacity	Package
LC651104N/F/L, LC651102N/F/L	30	4 k/2 k	256 W	DIP30S, DIP30S-D, MFP30S
LC65E1104	30	4 k	256 W	DIC30S, MFC30S
LC65P1104	30	4 k	256 W	DIP30S-D, MFP30S

Pin Assignment

Common to DIC/MFC



Usage Notes

The LC65E1104 was designed for developing and evaluating programs for the LC651104/1102 series microcontrollers. Keep the following points in mind when using the LC65E1104.

- 1. Protecting EPROM data from UV exposure
- Keep the LC65E1104's package window covered with an opaque seal when using the device.
- 2. The LC65E1104 differs from the LC651104N/F/L and LC651102N/F/L as listed in the table below.

	Item	LC65E1104	LC651104F/1102F	LC651104N/1102N	LC651104L/1102L
I/O circuit c	onfiguration	Open drain (N channel)		stor-provided output selectable b	
Port C and levels at res		High or low selected in 4-bit units (by EPROM data)	ł	High or low selected in 4-bit unit (user mask option)	5
Oscillator	Resonator	RC/ceramic (by EPROM data)		RC/ceramic (user mask option)	
Oscillator	Predivider option	1/1, 1/3, 1/4 (by EPROM data)	1/1 only (user mask option)	1/1, 1/3, 1/4 (user mask option)	
Watchdog I	reset	Available/not available (by EPROM data)		Available/not available (user mask option)	
Operating s voltage ran		3.0 to 6.0 V*	4.0 t 6.0 V	3.0 to 6.0 V	2.5 to 6.0 V
Normal mo	de current drain	Mask version + about 3 mA (typical)	2 mA (typical)	1.5 mA (typical)	1.5 mA (typical)
Low-level in (RES termi	nput current nal)	–50 μA (typical)		–10 μA (typical)	
Operating t	emperature range	+10 to +40°C		-40 to +85°C	
Package		DIC30S (with window) MFC30S (with window)		DIP30S, DIP30S-D MFP30S	

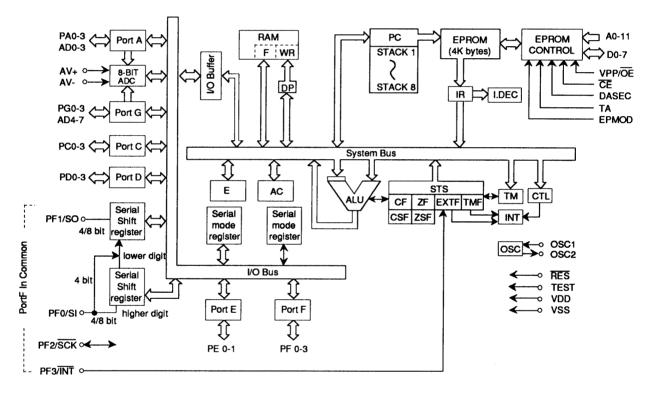
Note: A/D converter operating supply voltage range: 4.7 to 5.3 ${\rm V}$

Pin Names

OSC1, OSC2	RC or ceramic oscillator	TEST	Test
RES	Reset	INT	Interrupt request pin
PA0 to PA3	Shared-function I/O ports A0 to A3	SI	Serial input pin
PC0 to PC3	Shared-function I/O ports C0 to C3	SO	Serial output pin
PD0 to PD3	Shared-function I/O ports D0 to D3	SCK	Serial clock input/output pin
PE0 to PE1	Shared-function I/O ports E0 to E1	AD0 to AD7	AD converter input pin
PF0 to PF3	Shared-function I/O ports F0 to F3	AV+, AV–	AD converter reference voltage input
PG0 to PG3	Shared-function I/O ports G0 to G3	WDR	Watchdog reset pin

Note: The SI, SO, SCK, and INT pins are shared function pins that are also used as the PF0 to PF3 pins, respectively.

System Block Diagram



RAM	Data memory	ROM	Program memory
F	Flag	PC	Program counter
WR	Working register	INT	Interrupt control
AC	Accumulator	IR	Instruction register
ALU	Arithmetic and logic unit	I.DEC	Instruction decoder
DP	Data pointer	CF, ZSF	Carry flag, Carry save flag
E	E register	ZF, ZSC	Zero flag, zero save flag
CTL	Control register	EXTF	External interrupt request flag
OSC	Oscillator	TMF	Internal interrupt request flag
ТМ	Timer	STS	Status register

Pin Description

Symbol	Pins	I/O	Function	Option	At reset	PROM mode
V _{DD}	1	—	Power supply	_	_	_
V _{SS} OSC1/DASEC	1		Connections for the external RC or ceramic oscillator circuit used as the system clock oscillator. If external clock input is used, leave the	 Pin 2: RC oscillator external clock Pin 2: Ceramic oscillator Predivider option No predivider 		EPROM control signal DASEC
OSC2	1	0	OSC2 pin open.	 1/3 predivider 1/4 predivider 		
PA0/AD0/A1 PA1/AD1/A2 PA2/AD2/A3 PA3/AD3/A4	4	I/O	 I/O port: A0 to A3 Input in 4-bit units (IP instruction) Output in 4-bit units (OP instruction) Testing in single-bit units (BP and BNP instructions) Setting or clearing in single-bit units (SPB and RPB instructions) Standby is controlled by PA3 The PA3 pin must be free from chattering during the halt instruction execution cycle. Each of these four pins has two functions as listed below. PA0/AD0: AD converter input pin AD0 PA1/AD1: AD converter input pin AD1 PA2/AD2: AD converter input pin AD2 PA3/AD3: AD converter input pin AD3 	Open drain type output	High-level output (Output Nch transistor: Off)	Address inputs A1 to A4
PC0/D0 PC1/D1 PC2/D2 PC3/D3	4	I/O	 I/O port: C0 to C3 Identical to PA0 to PA3* Option permits output at reset to be high or low. Note: * No standby control function is provided. 	 Open drain type output Output at reset: high Output at reset: low 3.: Specified in a group of 4 bits 	 High-level output Low-level output (Option-selectable) 	Data lines D0 to D3
PD0/D4 PD1/D5 PD2/D6 PD3/D7	4	I/O	I/O port: D0 to D3 Identical to PC0 to PC3	Identical to PC0 to PC3	Identical to PC0 to PC3	Data lines D4 to D7
PE0/CE PE1/WDR/A0	2	I/O	 I/O port: E0 and E1 Input in 4-bit units (IP instruction) Output in 4-bit units (OP instruction) Setting or clearing in single-bit units (SPB, RPB instructions) Testing in single-bit units (BP and BNP instructions) PE0 provides a continuous burst (64-Tcyc) function. 	1. Open drain type output	High-level output (Output Nch transistor: Off)	 EPRO<u>M c</u>ontrol signal CE Address input A0
PF0/SI/A9 PF1/ <u>SO/A</u> 10 PF2/ <u>SCK</u> /A11 PF3/INT/TA	4	I/O	 I/O ports F0 tp F3 Identical to PE0 to PE1* Shared with the serial interface and INT input. Program-selectable SI Serial input port <u>SO</u> Serial output port <u>SCK</u> Serial clock input/output INT Interrupt request input The serial I/O function can be switched between 4-bit and 8-bit operation under program control. Note: * No burst pulse output function is provided. 	Identical to PE0 to PE1	Identical to PE0 to PE1 Serial port: Disabled Interrupt source: INT	 Address inputs A9 to A11 EPROM control signal TA

Continued on next page.

Continued from preceding page.

Symbol	Pins	I/O	Function	Option	At reset	PROM mode
PG0/AD4/A5 PG1/AD5/A6 PG2/AD6/A7 PG3/AD7/A8	4	I/O	 I/O ports G0 to G3 Identical to PE0 to PE1* Note: * No burst pulse output function is provided. Each of these four pins has two functions as listed below. PG0/AD4: AD converter input pin AD4 PG1/AD5: AD converter input pin AD5 PG2/AD6: AD converter input pin AD6 PG3/AD7: AD converter input pin AD7 	Identical to PE0 to PE1	Identical to PE0 to PE1	Address inputs A5 to A8
AV+	1	_	Reference voltage input pin for A/D			
AV-	1	_	conversion.	—	_	—
RES/VPP/OE	1		 System reset input Connect an external capacitor for power on reset. Apply a low level for at least 4 clock cycles for the power-on reset. 	_	_	EPR <u>QM</u> control signal VPP/OE
TEST/EPMOD	1		LSI test pin Normally connected to V _{SS}	_	_	EPROM control signal EPMOD

Oscillator circuit option

Option	Circuit	Conditions and notes
1. External clock		Leave the OSC2 pin open.
2. 2-pin RC OSC	Cext OSC 1 Cext OSC 1 Cext OSC 2 Cext O	
3. Ceramic oscillator	Ceramic OSC2	

Predivider option

Option	Circuit	Conditions and notes
1. No predivider (1/1)	OSC circuit Timing generator	 Applicable to all 3 oscillator options. The oscillator or external clock frequency must not exceed 1444 kHz. (LC651104N, LC651102N) The oscillator or external clock frequency must not exceed 4330 kHz. (LC651104F, LC651102F) The oscillator or external clock frequency must not exceed 1040 kHz. (LC651104L, LC651102L)
2. 1/3 predivider	ticsc 1/3 fosc Surger Solution	 Applicable to the external clock and ceramic oscillator options. The oscillator or external clock frequency must not exceed 4330 kHz.
3. 1/4 predivider	losc → 1/4 predivider → 0000 0000 → 0000 → 0000 → 0000 → 000000	 Applicable to the external clock and ceramic oscillator options. The oscillator or external clock frequency must not exceed 4330 kHz.

Note: The oscillator and predivider options are summarized in the LC651104/1102 semiconductor news.

Port C and D reset output level options

Either of the following two options may be selected for the C and D I/O ports. Note that these options are specified in 4bit units.

Option name	Conditions
1. Output at reset: high	All 4 bits of the selected port(s) (C or D or both)
1. Output at reset: low	All 4 bits of the selected port(s) (C or D or both)

Port output configuration option

All shared-function I/O ports have an open-drain output circuit in the LC65E1104.

Option	Circuit	Conditions and notes
1. Open drain output		Ports A, C, D, E and F

Watchdog reset option

This option specifies the use of the PE1/WDR pin. This pin can be specified to function either as the normal port PE1 or as the WDR watchdog reset pin.

Usage Notes

1. Option specification

The SU60K.EXE program is used for option specification. The option code for the option specification area (addresses 1000 to 100A (hexadecimal)) is created by assembling the output of the SU60K.EXE program using the Sanyo M60K.EXE macro assembler and then linking the macro assembler output with the Sanyo L60K.EXE linker. It is also possible to load data directly into the option specification area. Specify options according to the option code creation table on page 8.

2. PROM programming

LC65E1104 can be programmed with a general-purpose EPROM programmer using either the W65EP1104D or W65EP1104M adapter.

• Recommended EPROM programmers

Manufacturer	EPROM programmer
Advantest	R4945, R4944, R4943 or equivalent programmer
Ando	AF-9704
AVAL	_
Minato electronics	_

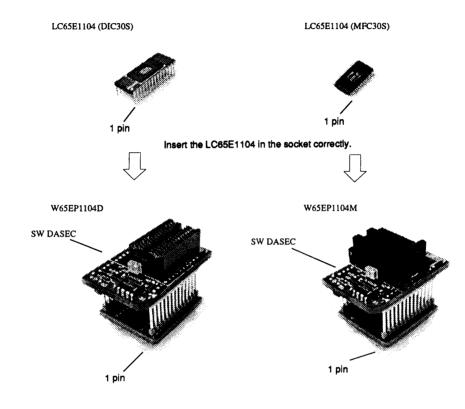
- The Intel 27512 (VPP: 12.5 V) high-speed programming method must be used to program this device. The address range must be set to 0 to 100A (hexadecimal) and the DASEC jumper must be set to the off position.
- 3. Using the data security function

The data security function prevents data already written to the microcontroller's PROM from being overwritten. LC651104 data security function procedure

- Move the DASEC jumper on the EPROM programming pin adapter to the on position. This enables the data security function.
- Attempt to reprogram the EPROM.

Since the data security function is enabled, the EPROM programmer will display an error. Note that this error is not due to an error in either the programmer or the LSI.

- Note: 1. At step 2, the data security function will not operate if all the data at the addresses to be programmed have the value FF (hexadecimal).
 - 2. At step 2, the data security function will not apply to (i.e., will not prevent) programming using the sequence BLANK Æ PROGRAM Æ VERIFY.
 - 3. Return the jumper to the off position after executing the data security function.



DASEC jumper setting

Normal data programming enabled
DASEC ON OFF

|--|

· Data security function enabled

DASEC	ON	OFF	

LC65E1104

Option specification area

ROM area	Bit		Option specified	Option/data relationship			
	7	Unused		0 (fixed)			
	6 Watchdog		g reset	0: Disabled, 1: Enabled			
1000H 5 4 3 2		PD					
		PC	Output level at reset	0: Low level, 1: High level			
		000					
		- OSC pre	divider (XX = bits 3, bit 2)	00: 1/1, 01: 1/3, 10: 1/4,. 11: unused			
	1						
0		OSC reso	onator (XX = bits 1, bit 0)	00: unused, 01: unused, 10: (2RC, EXT), 11: Ceramic			
	7	PC3					
	6	PC2	1				
	5	PC1	Output configuration	0: OD, 1: PU*			
	4	PC0					
1001H	3	PA3					
	2	PA2	-				
	1	PA1	Output configuration	0: OD, 1: PU*			
	0		-				
	7	PA0					
	6 Unused			0 (fixed)			
5	PE1						
	PE0	Output configuration	0: OD, 1: PU*				
1002H	1002H 4	PD3					
	2	PD2	-				
	1	PD1	Output configuration	0: OD, 1: PU*			
	0	PD0	-				
	7	PG3					
	6	PG2	-				
	5	PG1	Output configuration	0: OD, 1: PU*			
	4	PG0	-				
1003H	3	PG0 PF3					
	2	PF3 PF2	-				
	1	PF2 PF1	- Output configuration	0: OD, 1: PU*			
	0	PF1 PF0	-				
	7						
6							
1004H	5						
to	4	Unused		0 (fixed)			
100AH	3						
	2						
	1						
	0						

Note: Since all LC65E1104 ports are open-drain output circuits, the pull-up resistor options are ignored. However, the port options must be selected when using the LC651104/1102 mask ROM products. PU: Built-in pull-up resistor output circuit, OD: Open-drain output circuit

Specifications For LC651104N, 651102N Absolute Maximum Ratings at Ta = 25° C, V_{SS} = 0 V

Ratings Parameter Symbol Conditions Unit -0.3 to +7.0 Maximum supply voltage V_{DD} max V_{DD} V Allowable up to the OSC2 V Output voltage Vo generated voltage -0.3 to V_{DD} + 0.3 V_I1 OSC1*1 V Input voltage V_l2 TEST, RES, AV+, AV-–0.3 to V_{DD} + 0.3 V PC0 to PC3, PD0 to PD3, PE0, PE1, PF0 to PF3 V_{IO}1 -0.3 to +15 V Input/output voltage V_{IO}2 PA0 to PA3, PG0 to PG3 -0.3 to V_{DD} + 0.3 V Peak output current I/O port -2 to +20 mΑ lop I/O port: Per pin over a 100 ms period -2 to +20 mΑ IOA PC0 to PC3, PD0 to PD3, PE0, PE1:Total current for -15 to +100 $\Sigma I_{OA} 1$ mΑ Average output current PC0 to PC3, PD0 to PD3, and PE0, PE1*2 PF0 to PF3, PG0 to PG3, PA0 to PA3; Total current for $\Sigma I_{OA}2$ -15 to +100 mΑ PF0 to PF3, PG0 to PG3, and PA0 to PA3*2 Pd max1 Ta = +10 to +40°C (DIC package) 250 mW Allowable power dissipation Pd max2 Ta = +10 to +40°C (MFC package) mW 150 +10 to +40 °C Operating temperature Topr -55 to +125 °C Storage temperature Tstg

Allowable Operating Conditions at Ta = +10 to +40°C, $V_{SS} = 0 V$, $V_{DD} = 3.0$ to 6.0 V

Deveryor	Querchal			Ratings		
Parameter	Symbol	Conditions	min	typ	max	Unit
Operating supply voltage	V _{DD}	V _{DD}	3.0		6.0	V
Standby supply voltage	V _{ST}	V _{DD} : RAM, register hold*3	1.8		6.0	V
	V _{IH} 1	Port C, D, E, F: Output Nch Tr. off	0.7 V _{DD}		+13.5	V
	V _{IH} 2	Port A, G: Output Nch Tr. off	0.7 V _{DD}		V _{DD}	V
High level input voltage	V _{IH} 3	INT, SCK, SI: Output Nch Tr. off	0.8 V _{DD}		+13.5	V
	V _{IH} 4	$\overline{\text{RES}}$: V _{DD} = 1.8 to 6 V	0.8 V _{DD}		V _{DD}	V
	V _{IH} 5	OSC1: External clock mode	0.8 V _{DD}		V _{DD}	V
	V _{IL} 1	Port: Output Nch Tr. off, V _{DD} = 4 to 6 V	V _{SS}		0.3 V _{DD}	V
	V _{IL} 2	Port: Output Nch Tr. off, V _{DD} = 3 to 6 V	V _{SS}		0.25 V _{DD}	V
	V _{IL} 3	$\overline{\text{INT}}$, $\overline{\text{SCK}}$, SI: Output Nch Tr. off, V_{DD} = 4 to 6 V	V _{SS}		0.25 V _{DD}	V
	V _{IL} 4	$\overline{\text{INT}}$, $\overline{\text{SCK}}$, SI: Output Nch Tr. off, V_{DD} = 3 to 6 V	V _{SS}		0.2 V _{DD}	V
I and land in a track and	V _{IL} 5	OSC1: External clock mode, V _{DD} = 4 to 6 V	V _{SS}		0.25 V _{DD}	V
Low level input voltage	V _{IL} 6	OSC1: External clock mode, V _{DD} = 3 to 6 V	V _{SS}		0.2 V _{DD}	V
	V _{IL} 7	TEST: $V_{DD} = 4 \text{ to } 6 \text{ V}$	V _{SS}		0.3 V _{DD}	V
	V _{IL} 8	TEST: V _{DD} = 3 to 6 V	V _{SS}		0.25 V _{DD}	V
	V _{IL} 9	$\overline{\text{RES}}$: V _{DD} = 4 to 6 V	V _{SS}		0.25 V _{DD}	V
	V _{IL} 10	$\overline{\text{RES}}$: V _{DD} = 3 to 6 V	V _{SS}		0.2 V _{DD}	V
Operating frequency (cycle time)	fop (Tcyc)	When the 1/3 or 1/4 predivider option is selected, clock must not exceed 4.33 MHz. V _{DD} = 3 to 6 V	200 (20)		1444 (2.77)	kHz (µs)
[External clock conditions]						
Frequency	text	OSC1: Fig 1, when clock exceeds 1.444 MHz,	200		4330	kHz
Pulse width	textH, textL	the 1/3 or 1/4 predivider option must be selected.	69			ns
Rise/fall time	textR, textF	$V_{DD} = 3 \text{ to } 6 \text{ V}$			50	ns
[Oscillator guaranteed constants]	1			1	1	
	Cext	OSC1, OSC2: Fig 2, V _{DD} = 3 to 6 V		270 ± 5%		pF
	Cext	OSC1, OSC2: Fig 2, V _{DD} = 4 to 6 V		270 ± 5%		pF
2-pin RC oscillator	Rext	OSC1, OSC2: Fig 2, V _{DD} = 3 to 6 V		12 ± 1%		kΩ
	Rext	OSC1, OSC2: Fig 2, V _{DD} = 4 to 6 V		4.7 ± 1%		kΩ
Ceramic		Fig 3		Table 1		

Electrical Characteristics at Ta = +10 to +40 $^{\circ}C,$ V_{SS} = 0 V, V_{DD} = 3.0 to 6.0 V

Parameter	Symbol Conditions		Ratings			
Farameter	Symbol	Conditions	min	typ	max	Unit
	I _{IH} 1	Port C, D, E, F: Output Nch Tr. off (including off leak current of Nch Tr.), V_{IN} = +13.5			+5.0	μA
High-level input current	I _{IH} 2	Port A, G: Output Nch Tr. off (including off leak current of Nch Tr.), V _{IN} = V _{DD}			+5.0	μA
	I _{IH} 3	OSC1: External clock mode, V _{IN} = V _{DD}			+1.0	μA
	I _{IL} 1	Port: Output Nch Tr. off, V _{IN} = V _{SS}	-1.0			μA
Low-level input current	I _{IL} 2	RES: V _{IN} = V _{SS}	-150	-50		μA
	I _{IL} 3	OSC1: External clock mode, V _{IN} = V _{SS}	-1.0			μA
	V _{OL} 1	Port: I_{OL} = 10 mA, V_{DD} = 4.0 to 6.0 V			1.5	V
Low-level output current	V _{OL} 2	Port: I_{OL} = 1 mA, I_{OL} of each port; 1 mA or less V_{DD} = 3.0 to 6.0 V			0.5	v
[Schmitt characteristics]						
Hysteresis voltage	VHIS			0.1 V _{DD}		V
High-level threshold voltage	VtH	RES, INT, SCK, SI, OSC1 of Schmitt type*4	0.4 V _{DD}		0.8 V _{DD}	V
Low-level threshold voltage	VtL		0.2 V _{DD}		0.6 V _{DD}	V
[Current dissipation]	·			·		
2-pin RC oscillator	IDDOP1	V_{DD} : Output Nch Tr. off at operating, port = V_{DD} , Fig. 2, fosc = 900 kHz (typ)		4.5	6	mA
	IDDOP2	V _{DD} : Fig 3, 4 MHz, 1/3 predivider		4.5	7	mA
	IDDOP3	V _{DD} : Fig 3, 4 MHz, 1/4 predivider		4.5	6	mA
Ceramic oscillator	IDDOP4	V _{DD} : Fig 3, 400 kHz		4.0	4.5	mA
	IDDOP5	V _{DD} : Fig 3, 800 kHz		4.5	6	mA
External clock	IDDOP6	V _{DD} : 200 kHz to 1444 kHz, 1/1 predivider; 600 kHz to 4330 kHz, 1/3 predivider; 800 kHz to 4330 kHz, 1/4 predivider		4.5	7	mA
		V_{DD} : Output Nch Tr. off, $V_{DD} = 6 V$		0.05	10	μA
Standby mode	IDDst	V_{DD} : Port = V_{DD} , V_{DD} = 3 V		0.025	5	μA
[Oscillator characteristics]						
		OSC1, OSC2: Fig 3, fo = 400 kHz	384	400	416	kHz
	fCFOSC*5	OSC1, OSC2: Fig 3, fo = 800 kHz	768	800	832	kHz
Ceramic OSC frequency		OSC1, OSC2: Fig 3, fo = 1 MHz	960	1000	1040	kHz
		OSC1, OSC2: Fig 3, fo = 4 MHz, 1/3 predivider, 1/4 predivider	3840	4000	4160	kHz
		Fig 4, fo = 400 kHz			10	ms
Stabilization	tCFS	Fig 4, fo = 800 kHz, 1 MHz, 4 MHz, 1/3 predivider, 1/4 predivider			10	ms
2-pin RC oscillator	#1000	OSC1, OSC2: Fig. 2, Cext = 270 pF ± 5%, Fig. 2, Rext = 4.7 kΩ ± 1%, V_{DD} = 4 to 6 V	666	900	1334	kHz
frequency	fMOSC	OSC1, OSC2: Fig. 2, Cext = 270 pF ± 5%, Fig. 2, Rext = 12 kΩ ± 1%, V _{DD} = 3 to 6 V	283	400	717	kHz
[Pull-up resistance]						
I/O port RES:	RU	$\overline{\text{RES}}$: V _{IN} = V _{SS} , V _{DD} = 5 V	50	100	250	kΩ
[External reset characteristics]						
Reset time	tRST			See Fig. 5		
Pin capacitance	CP	f = 1 MHz. V_{IN} = V_{SS} for all pins other than those being tested.		10		pF
[Serial clock]						_
Input clock cycle time	tCKCY1	SCK: Fig. 6	3.0			μs
Output clock cycle time	tCKCY2	SCK: Fig. 6		$64 imes tCYC^{*6}$		μs
Input clock low-level pulse width	tCKL1	SCK: Fig. 6	1.0			μs
Output clock low-level pulse width	tCKL2	SCK: Fig. 6		$32 \times tCYC$		μs
Input clock high-level pulse width	tCKH1	SCK: Fig. 6	1.0			μs
Output clock high-level pulse width	tCKH2	SCK: Fig. 6		$32 \times tCYC$		μs
[Serial input]						
Data setup time	tICK	SI: Specified from the rising edge of SCK. Fig. 6	0.4			μs
	tCKI		0.4		1	1

Continued from preceding page.

Parameter	Symbol	Conditions	Ratings			Unit	
i arameter	Gymbol			typ	max	Onic	
[Serial output]		1					
Output delay time	tCKO	SO: Specified from the falling edge of \overline{SCK} . Nch OD only, external 1k Ω , external 50 pF, Fig. 6			0.6	μs	
[Pulse output]							
Period	tPCY			64 ×tCYC		μs	
High-level pulse width	tPH	PE0: Fig. 7, tCYC = 4 × system clock period, Nch OD only, external 1 kΩ, external 50 pF		32 × tCYC ± 10%		μs	
Low-level pulse width	tPL			32 × tCYC ± 10%		μs	
[AD conversion characteristics]	•		·				
Resolution		V _{DD} = 4.7 to 5.3 V		8		bits	
Absolute accuracy		$AV+ = V_{DD}, AV- = V_{SS}, V_{DD} = 4.7 \text{ to } 5.3 \text{ V}$		±1	±2	LSB	
Conversion time TCA	TOAD	AD speed 1/1, at 26 \times tCYC, V _{DD} = 4.7 to 5.3 V	72 (tCYC = 2.77 μs)		312 (tCYC = 12 μs)		
		AD speed 1/2, at 51 \times tCYC, V _{DD} = 4.7 to 5.3 V	141 (tCYC = 2.77 μs)		612 (tCYC = 12 μs)	μs	
	AV+	AV+: V _{DD} = 4.7 to 5.3 V	AV-		V _{DD}	v	
Reference input voltage AV		AV-: V _{DD} = 4.7 to 5.3 V	V _{SS}		AV+	V	
Reference input current range	IRIF	AV+, AV–: AV+ = V_{DD} , V_{DD} = 4.7 to 5.3 V, AV– = V_{SS}	75	150	300	μA	
Analog input voltage range	VAIN	AD0 to AD7: V _{DD} = 4.7 to 5.3 V	AV-		AV+	V	
Analog port input current	IAIN	Port pins AD0 to AD7 Including output OFF leakage current. VAIN = V_{DD} , V_{DD} = 4.7 to 5.3 V			1	μA	
		Port pins AD0 to AD7 VAIN = V_{SS} , V_{DD} = 4.7 to 5.3 V	-1				
[Watchdog timer]	•						
	Cw	WDR: V _{DD} = 3 to 6 V		0.1 ± 5%		μF	
Guaranteed constant*7	Rw	WDR: V _{DD} = 3 to 6 V		680 ± 1%		kΩ	
	RI	WDR: $V_{DD} = 3 \text{ to } 6 \text{ V}$		100 ± 1%		Ω	
Clear time (discharge)	tWCT	WDR: Fig. 8, V _{DD} = 3 to 6 V	100			μs	
Clear time (charge)	tWCCY	WDR: Fig. 8, V _{DD} = 3 to 6 V	36			ms	
	Cw	WDR: $V_{DD} = 4 \text{ to } 6 \text{ V}$		0.047 ± 5%		μF	
Guaranteed constant*7	Rw	WDR: $V_{DD} = 4 \text{ to } 6 \text{ V}$		680 ± 1%		kΩ	
	RI	WDR: $V_{DD} = 4 \text{ to } 6 \text{ V}$		100 ± 1%		Ω	
Clear time (discharge)	tWCT	WDR: Fig. 8, V _{DD} = 4 to 6 V	40			μs	
Clear time (charge)	tWCCY	WDR: Fig. 8, V _{DD} = 4 to 6 V	18			ms	

Note: 1. The LC65E1104 will accept input voltages up to the generated oscillator amplitude if the oscillator circuit in figure 4 with circuit constants in the guaranteed constants ranges is driven from within the IC.

2. Average over a 100 ms period

The operating supply voltage V_{DD} must be held until standby mode is enterd after the execution of a HALT instruction. The PA3 pin must be free from chattering during the HALT instruction cycle.

4. The OSC1 pin input circuit has Schmitt trigger characteristics when the 2-terminal RC oscillator option or the external clock oscillator option is selected.

5. fCFOSC: oscillator frequency. The center frequency of a ceramic oscillator has a tolerance range of about 1% around the nominal value specified by the manufacturer of the oscillator element. For details, refer to the specifications of the ceramic resonator.

6. TCYC = $4 \times$ system clock period

7. If the LC65E1104 is used in an environment subject to condensation, leakage between PE1 and adjacent pins and leakage associated with external RCA circuits require special attention.

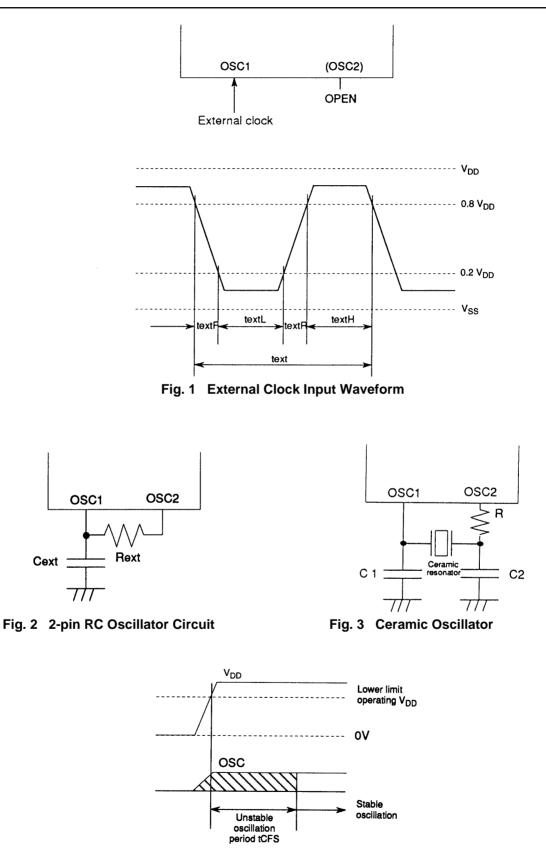
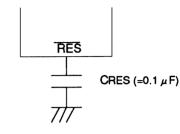


Fig. 4 Oscillator Stabilization Period

Table 1 Constants Guaranteed for Ceramic Resonator Oscillator

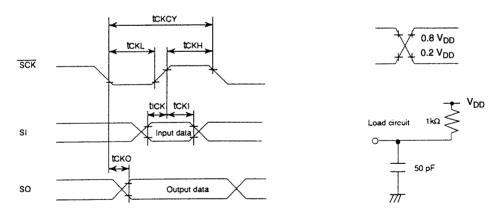
4 MHz (Murata)	C1	33 pF ± 10%
CSA4.00MG	C2	33 pF ± 10%
CST4.00MGW (built-in C)	R	0 Ω
4 MHz (Kyocera)	C1	33 pF ± 10%
KBR4.0 MSA	C2	33 pF ± 10%
KBR4.0MKS (built-in C)	R	0 Ω
	C1	100 pF ± 10%
1 MHz (Murata) CSB1000J	C2	100 pF ± 10%
	R	2.2 kΩ
	C1	100 pF ± 10%
1 MHz (Kyocera) KBR1000F	C2	100 pF ± 10%
	R	0 kΩ
	C1	100 pF ± 10%
800 kHz (Murata) CSB800J	C2	100 pF ± 10%
	R	2.2 kΩ
	C1	220 pF ± 10%
800 kHz (Kyocera) KBR800F	C2	220 pF ± 10%
	R	0 kΩ
	C1	220 pF ± 10%
400 kHz (Murata) CSB400P	C2	220 pF ± 10%
	R	2.2 kΩ
	C1	330 pF ± 10%
400 kHz (Kyocera) KBR400BK	C2	330 pF ± 10%
	R	0 kΩ

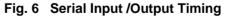


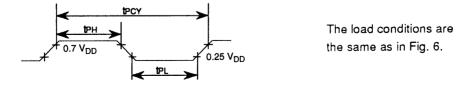


Note: When the rise time of the power supply is close to 0, the reset time will be between 10 and 100 ms for a CRES of $0.5 \ \mu\text{F}$. If the rise time of the power supply is significantly longer, the value of CRES must be increased so that the reset time will be 10 ms or longer.

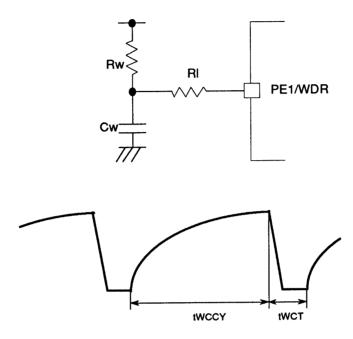
Note: The constants above are preliminarlly. Final ratings will be fixed after evaluation.











Note: 1. tWCCT: The charge time due to the time constant of the external Cw, Rw, and R1 components 2. tWCT: The discharge time due to program operation

Fig. 8 Watchdog Timer Waveform

For LC651104F, 651102F Absolute Maximum Ratings at $Ta=25^{\circ}C,\,V_{SS}$ = 0 V

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V _{DD} max	V _{DD}	-0.3 to +7.0	V
Output voltage	Vo	OSC2	Allowable up to the generated voltage	V
	V _I 1	OSC1*1	-0.3 to V _{DD} + 0.3	V
Input voltage	V _l 2	TEST, RES, AV+, AV-	-0.3 to V _{DD} + 0.3	V
	V _{IO} 1	PC0 to PC3, PD0 to PD3, PE0, PE1, PF0 to PF3	-0.3 to +15	V
Input/output voltage	V _{IO} 2	PA0 to PA3, PG0 to PG3	-0.3 to V _{DD} + 0.3	V
Peak output current	I _{OP}	I/O port	-2 to +20	mA
	I _{OA}	I/O port: Per pin over a 100 ms period	-2 to +20	mA
Average output current	Σl _{OA} 1	PC0 to PC3, PD0 to PD3, PE0, PE1:Total current for PC0 to PC3, PD0 to PD3, and PE0, PE1*2	-15 to +100	mA
	Σl _{OA} 2	PF0 to PF3, PG0 to PG3, PA0 to PA3: Total current for PF0 to PF3, PG0 to PG3, and PA0, PA3*2	-15 to +100	mA
Allowship newer dissinction	Pd max1	Ta = +10 to +40°C (DIC package)	250	mW
Allowable power dissipation	Pd max2	Ta = +10 to +40°C (MFC package)	150	mW
Operating temperature	Topr		+10 to +40	°C
Storage temperature	Tstg		-55 to +125	°C

Allowable Operating Conditions at Ta = +10 to +40 $^{\circ}C,$ V_{SS} = 0 V, V_{DD} = 4.0 to 6.0 V

Deservation	Querrah al	Conditions		Ratings		Unit	
Parameter	Symbol	Conditions	min	typ	max		
Operating supply voltage	V _{DD}	V _{DD}	4.0		6.0	V	
Standby supply voltage	VST	V _{DD} : RAM, register hold*3	1.8		6.0	V	
	V _{IH} 1	Port C, D, E, F: Output Nch Tr. OFF	0.7 V _{DD}		+13.5	V	
	V _{IH} 2	Port A, G: Output Nch Tr. OFF	0.7 V _{DD}		V _{DD}	V	
High-level input voltage	V _{IH} 3	INT, SCK, SI: Output Nch Tr. OFF	0.8 V _{DD}		+13.5	V	
	V _{IH} 4	RES: V _{DD} = 1.8 to 6.0 V	0.8 V _{DD}		V _{DD}	V	
	V _{IH} 5	OSC1: External clock mode	0.8 V _{DD}		V _{DD}	V	
	V _{IL} 1	Port: Output Nch Tr. OFF	V _{SS}		0.3 V _{DD}	V	
	V _{IL} 2	INT, SCK, SI: Output Nch Tr. OFF	V _{SS}		0.25 V _{DD}	V	
Low-level input voltage	V _{IL} 3	OSC1: External clock	V _{SS}		0.25 V _{DD}	V	
	V _{IL} 4	TEST	V _{SS}		0.3 V _{DD}	V	
	V _{IL} 5	RES	V _{SS}		0.25 V _{DD}	V	
Operating frequency (cycle time)	fOP (Tcyc)		200 (20)		4330 (0.92)	kHz (µs)	
[External clock conditions]							
Frequency	text		200		4330	kHz	
Pulse width	textH, textL	OSC1: Fig. 1	69			ns	
Rise/fall time	textR, textF	OSC1: Fig. 1			50	ns	
Oscillation guaranteed constants ceramic resonator oscillator		Fig. 2	See Table 1				

Electrical Characteristics at Ta = +10 to +40 $^{\circ}C,$ V_{SS} = 0 V, V_{DD} = 4.0 to 6.0 V

Deremeter	Symbol		Ratings			
Parameter	Symbol	Conditions	min	typ	max	Unit
	I _{IH} 1	Port C, D, E, F: Output Nch Tr. OFF, (Including the Nch. transistor off state leakage current.), $V_{IN} = +13.5$			+5.0	μA
High-level input current	I _{IH} 2	Port A, G: Output Nch Tr. OFF, (Including the Nch. transistor off state leakage current.), $V_{IN} = V_{DD}$			+5.0	μA
	I _{IH} 3	OSC1: External clock mode, V _{IN} = V _{DD}			+1.0	μA
	I _{IL} 1	Port of OD type: Output Nch Tr. OFF, V _{IN} = V _{SS}	-1.0			μA
Low-level input current	I _{IL} 2	$\overline{\text{RES}}$: V _{IN} = V _{SS}	-150	-50		μA
	I _{IL} 3	OSC1: External clock mode, V _{IN} = V _{SS}	-1.0			μA
	V _{OL} 1	Port: I _{OL} = 10 mA			1.5	V
Low-level output voltage	V _{OL} 2	Port: $I_{OL} = 1 \text{ mA}$, I_{OL} of each port; 1 mA or less			0.5	V
[Schmitt characteristics]						
Hysteresis voltage	VHIS			0.1 V _{DD}		V
High-level threshold voltage	VtH	RES, INT, SCK, SI, OSC1 of Schmitt type*4	0.4 V _{DD}		0.8 V _{DD}	V
Low-level threshold voltage	VtL		0.25 V _{DD}		0.6 V _{DD}	V
[Current drain]						
Ceramic resonator oscillator	IDDOP1	V _{DD} : Fig. 2, 4 MHz, 200 kHz to 4330 kHz*		5	8	mA
	IPOOPI	Note: * Output Nch Tr. OFF at operating mode,		5	o	
External clock	IDDOP2	port = V_{DD}		5	8	mA
				0.05	40	
Standby mode	IDDst	V_{DD} : Output Nch Tr. OFF, $V_{DD} = 6 V$		0.05	10	μA
		V_{DD} : Port = V_{DD} , V_{DD} = 3 V		0.025	5	μA
[Oscillator characteristics]	(05000		00.40	4000	4400	
Ceramic resonator oscillator	fCFOSC	OSC1, OSC2: Fig.2, fo = 4 MHz*5	3840	4000	4160	kHz
Frequency stabilization time	tCFS	Fig. 3, fo = 4 MHz			10	ms
[Pull-up resistance]			50	400	050	
I/O port RES	RU	$\overline{\text{RES}}$: V _{IN} = V _{SS} , V _{DD} = 5 V	50	100	250	kΩ
[External reset characteristics]	(DOT	1				
Reset time	tRST			See Fig. 4		
Pin capacitance	CP	f = 1 MHz. $V_{IN} = V_{SS}$ for all pins other than those being tested.		10		pF
[Serial clock]		1	1			
Input clock cycle time	tCKCY1	SCK: Fig. 5	2.0			μs
Output clock cycle time	tCKCY2	SCK: Fig. 5		$64 \times tCYC^{*6}$		μs
Input clock low-level pulse width	tCKL1	SCK: Fig. 5	0.6			μs
Output clock low-level pulse width	tCKL2	SCK: Fig. 5		$32 \times tCYC$		μs
Input clock high-level pulse width	tCKH1	SCK: Fig. 5	0.6			μs
Output clock high-level pulse width	tCKH2	SCK: Fig. 5		$32 \times tCYC$		μs
[Serial input]		1	1			
Data setup time	tICK	SI: Specified from the rising edge of SCK. Fig. 5	0.2			μs
Data hold time	tCKI		0.2			μs
[Serial output]			1			
Output delay time	tCKO	SO: Specified from the falling edge of SCK. Nch OD only, external 1 k Ω , external 50 pF, Fig.5			0.4	μs
[Pulse output]						
Period	tPCY			$64 \times tCYC$		μs
High-level pulse width	tPH	PE0: Fig. 6, tCYC = 4 × system clock period, Nch OD only, external 1 kΩ, external 50 pF		32 × tCYC ± 10%		μs
Low-level pulse width	tPL			32 × tCYC ± 10%		μs

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Parameter	Cumbel	Conditions		Linit		
Parameter	Symbol Conditions -		min	typ	max	Unit
[AD conversion characteristics]			•		•	
Resolution		V _{DD} = 4.7 to 5.3 V		8		bits
Absolute accuracy		AV+ = V_{DD} , AV- = V_{SS} , V_{DD} = 4.7 to 5.3 V		±1	±2	LSE
Conversion time	+CAD	AD speed 1/1, at 26 × tCYC, V_{DD} = 4.7 to 5.3 V	25 (tCYC = 0.98 μs)		312 (tCYC = 12 μs)	μs
Conversion time	tCAD AD speed 1/2, at 51 \times tCYC, V _{DD} = 4.7 to 5.3 V	50 (tCYC = 0.98 μs)		612 (tCYC = 12 μs)	μs	
Poforonoo input voltago	AV+ AV+: V _{DD} = 4.7 to 5.3 V		AV–		V _{DD}	v
Reference input voltage	AV-	AV-: V _{DD} = 4.7 to 5.3 V	V _{SS}		AV+	1 ^v
Reference input current range	IRIF	AV+, AV–: AV+ = V_{DD} , V_{DD} = 4.7 to 5.3 V, AV– = V_{SS}	75	150	300	μA
Analog input voltage range	VAIN	AD0 to AD7: V_{DD} = 4.7 to 5.3 V	AV-		AV+	V
Analog port input current	IAIN	Port pins AD0 to AD7 Including output OFF leakage current. VAIN = V_{DD} , V_{DD} = 4.7 to 5.3 V			1	μA
		Port pins AD0 to AD7 VAIN = V_{SS} , V_{DD} = 4.7 to 5.3 V	-1			
[Watchdog timer]						
	Cw	WDR		0.01 ± 5%		μF
Guaranteed constants	Rw	WDR		680 ± 1%		kΩ
	RI	WDR		100 ± 1%		Ω
Clear time (discharge)	tWCT	WDR: Fig. 7	10			μs
Clear time (charge)	tWCCY	WDR: Fig. 7	42			ms

Note: 1. The LC65E1104 will accept input voltages up to the generated oscillator amplitude if the oscillator circuit in figure 2 with circuit constants in the guaranteed constants ranges is driven internally.

2. Average over a period of 100 ms.

3. The operating supply voltage V_{DD} must be held until standby mode is entered after the execution of a HALT instruction. The PA3 pin must be free from chattering during the HALT instruction execution cycle.

4. The OSC1 pin input circuit has Schmitt trigger characteristics when the external clock oscillator option is selected.

5. fCFOSC: Oscillator frequency

6. TCYC = $4 \times$ system clock period

7. If the LC65E1104 is used in an environment subject to condensation, leakage between PE1 and adjacent pins and leakage associated with external RCA circuits require special attention.

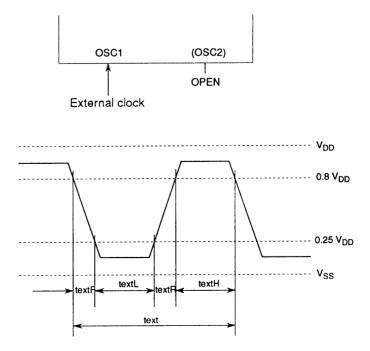


Fig. 1 External Clock Input Waveform

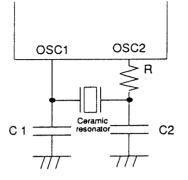
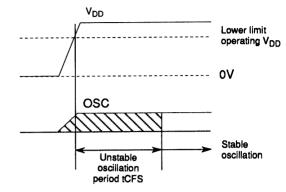


Fig. 2 Ceramic Oscillator Circuit







4 MHz (Murata)	C1	33 pF ± 10%
CSA4.00MG	C2	33 pF ± 10%
CST4.00MGW (built-in C)	R	0 Ω
4 MHz (Kyocera)	C1	33 pF ± 10%
KBR4.0 MSA	C2	33 pF ± 10%
KBR4.0MKS (built-in C)	R	0 Ω

Note: The constants above are preliminarly. Final ratings will be fixed after evaluation.

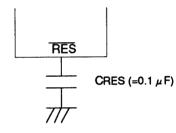


Fig. 4 Reset Circuit

Note: When the rise time of the power supply is close to 0, the reset time will be between 10 and 100 ms for a CRES of $0.5 \ \mu\text{F}$. If the rise time of the power supply is significantly longer, the value of CRES must be increased so that the reset time will be 10 ms or longer.

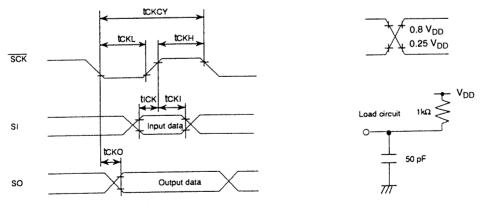


Fig. 5 Serial Input /Output Timing

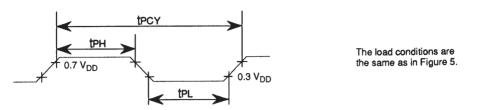
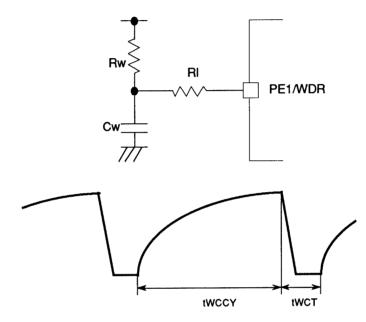


Fig. 6 Pulse Output Timing at Port PE0



Note: 1. tWCCY: The charge time due to the time constant of the external Cw, Rw, and R1 components 2. tWCT: The discharge time due to program operation



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